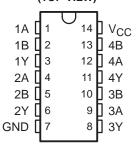
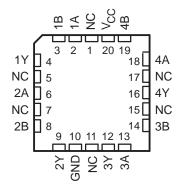
- 4.5-V to 5.5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V

SN54ACT32...J OR W PACKAGE SN74ACT32...D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



- Max t_{pd} of 10 ns at 5 V
- Inputs Are TTL-Voltage Compatible

SN54ACT32 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

The 'ACT32 devices are quadruple 2-input positive-OR gates. The devices perform the Boolean function Y = A + B or $Y = \overline{A} \bullet \overline{B}$ in positive logic.

ORDERING INFORMATION

TA	PACKAGI	ΕŤ	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74ACT32N	SN74ACT32N
	colo p	Tube	SN74ACT32D	ACTOO
	SOIC - D	Tape and reel	SN74ACT32DR	ACT32
-40°C to 85°C	SOP - NS	Tape and reel	SN74ACT32NSR	ACT32
	SSOP – DB	Tape and reel	SN74ACT32DBR	AD32
	TOCOD DW	Tube	SN74ACT32PW	ADOO
	TSSOP – PW	Tape and reel	SN74ACT32PWR	AD32
	CDIP – J	Tube	SNJ54ACT32J	SNJ54ACT32J
-55°C to 125°C	CFP – W	Tube	SNJ54ACT32W	SNJ54ACT32W
	LCCC - FK	Tube	SNJ54ACT32FK	SNJ54ACT32FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Υ
Н	Χ	Н
X	Н	Н
L	L	L



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logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		
Output voltage range, VO (see Note 1)		1.000000000000000000000000000000000000
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)		±20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	c)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	-	±50 mA
Continuous current through V _{CC} or GND		±200 mA
Package thermal impedance, θ _{JA} (see Note 2):	: D package	86°C/W
	DB package	96°C/W
	N package	80°C/W
	NS package	76°C/W
	PW package	113°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		SN54ACT32		SN74A	CT32	
		MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	in	2		V
VIL	Low-level input voltage		0.8		8.0	V
VI	Input voltage	0	Vcc	0	VCC	V
VO	Output voltage	0	VCC	0	VCC	V
ЮН	High-level output current	ng	-24		-24	mA
loL	Low-level output current	08	24		24	mA
Δt/Δν	Input transition rise or fall rate	7	8		8	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEGT GOVERNO	.,	T	A = 25°C	;	SN54A	CT32	SN74A	CT32	UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
	L 50 A	4.5 V	4.4			4.4		4.4		
	$IOH = -50 \mu A$	5.5 V	5.4			5.4		5.4		
.,	044	4.5 V	3.86			3.7		3.76		.,
VOH	I _{OH} = -24 mA	5.5 V	4.86			4.7		4.76		V
	I _{OH} = -50 mA [†]	5.5 V				3.86				
	I _{OH} = -75 mA [†]	5.5 V					EN	3.85		
	I _{OL} = 50 μA	4.5 V		0.001	0.1		0.1		0.1	
		5.5 V		0.001	0.1	.<	0.1		0.1	
.,	I _{OL} = 24 mA	5.5 V			0.36	Ć)	0.5		0.44	V
VOL		5.5 V			0.36	200	0.5		0.44	
	$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				A.	1.65			
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V							1.65	
lį	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μΑ
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		40		20	μΑ
∆l _{CC} ‡	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V		0.6	·		1.6		1.5	mA
C _i	V _I = V _{CC} or GND	5 V		2.6						pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V $\,\pm\,$ 0.5 V (unless otherwise noted) (see Figure 1)

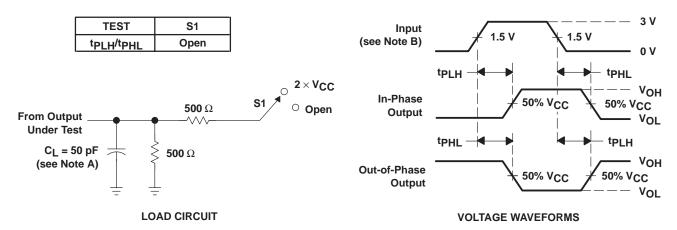
DADAMETER	FROM	то	T _A = 25°C			SN54ACT32	SN74ACT32		
PARAMETER	(INPUT)	UT) (OUTPUT)	MIN	TYP	MAX	MIN MAX	MIN	MAX	UNIT
^t PLH	A on D	V	1	6.5	9	SEOFAIL	1	10	no
t _{PHL}	A or B	ī	1	6.5	9	Sk.	1	10	ns

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST C	TYP	UNIT	
C _{pd}	Power dissipation capacitance	C _L = 50 pF,	f = 1 MHz	40	pF

[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5$ ns. $t_f \leq 2.5$ ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ACT32D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT32	Samples
SN74ACT32DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD32	Samples
SN74ACT32DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT32	Samples
SN74ACT32DRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT32	Samples
SN74ACT32N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74ACT32N	Samples
SN74ACT32NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT32	Samples
SN74ACT32PW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD32	Samples
SN74ACT32PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD32	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

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(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

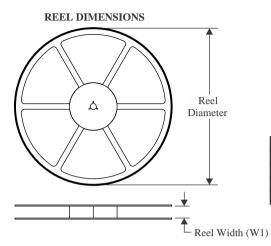
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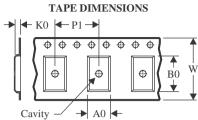
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PACKAGE MATERIALS INFORMATION

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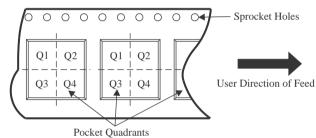
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

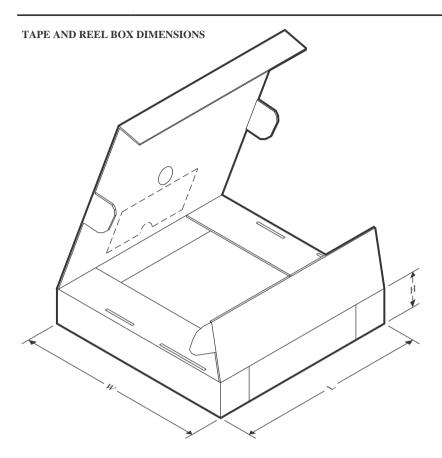
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT32DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74ACT32DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ACT32NSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74ACT32PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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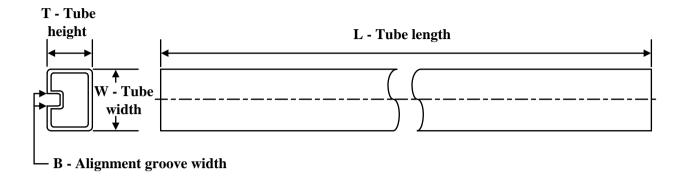
*All dimensions are nominal

7 III GIII I GII GI GI GI GI GI GI GI GI							
Device	Package Type	Package Drawing	Pins	Pins SPQ Length (mr		Width (mm)	Height (mm)
SN74ACT32DBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74ACT32DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74ACT32NSR	SO	NS	14	2000	356.0	356.0	35.0
SN74ACT32PWR	TSSOP	PW	14	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE

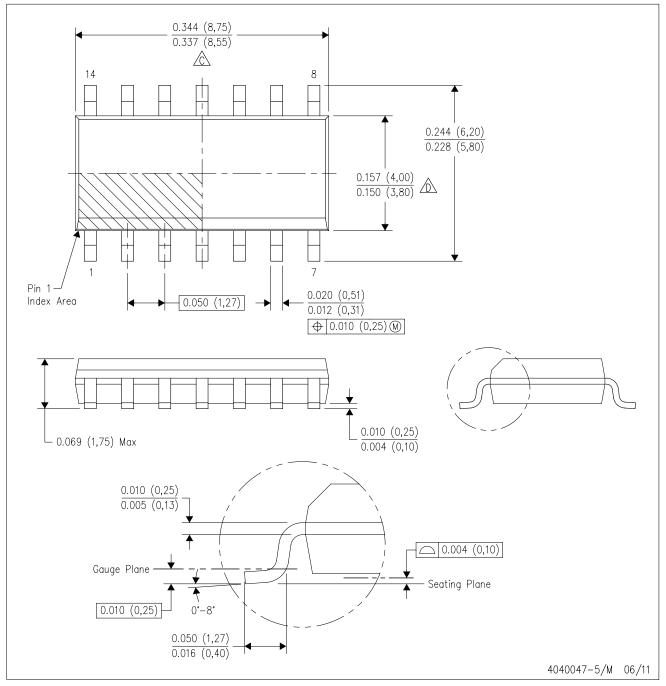


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ACT32D	D	SOIC	14	50	506.6	8	3940	4.32
SN74ACT32N	N	PDIP	14	25	506	13.97	11230	4.32
SN74ACT32N	N	PDIP	14	25	506	13.97	11230	4.32
SN74ACT32PW	PW	TSSOP	14	90	530	10.2	3600	3.5

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

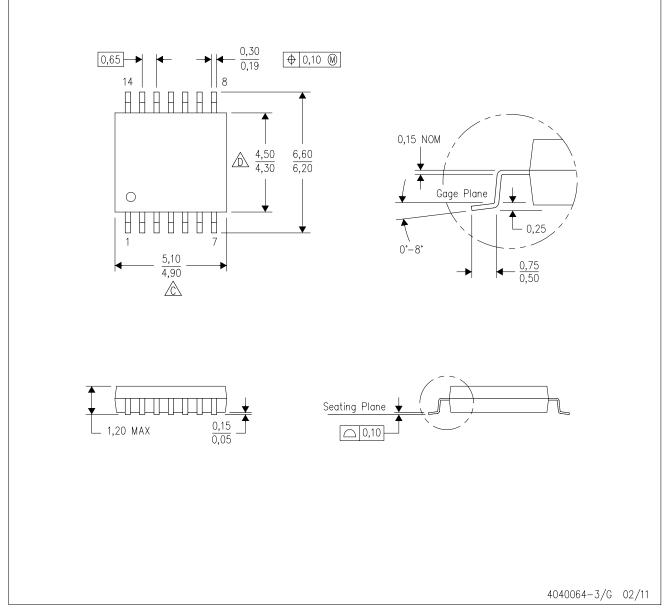


- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



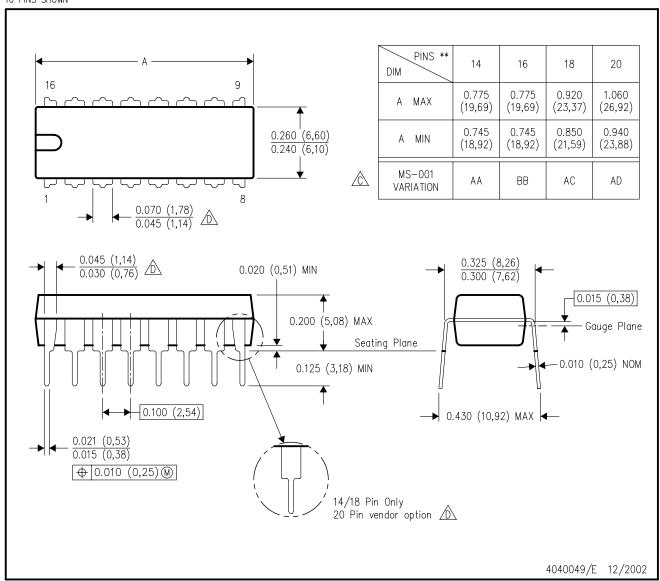
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

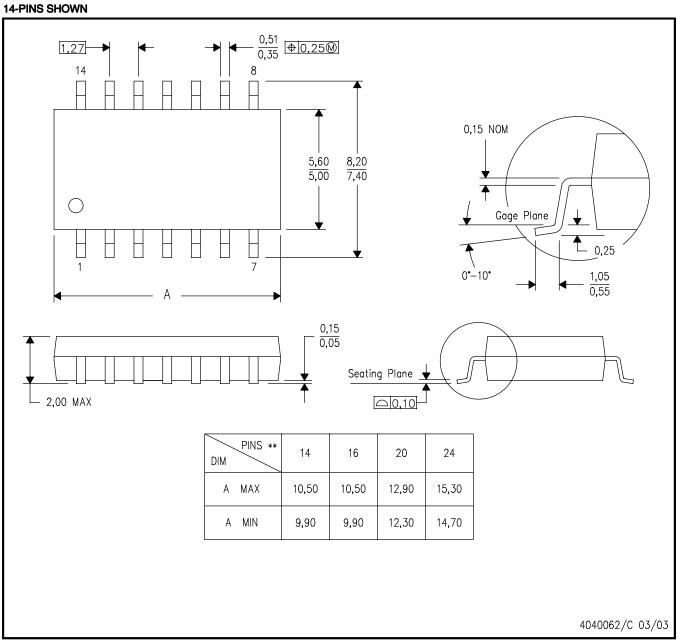
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE



- All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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74LVC2G00HD4-7 NL17SG02P5T5G 74LVC2G86HK3-7 NLVVHC1G14DFT2G NLX1G99DMUTWG NLVVHC1G00DFT2G
NLV7SZ57DFT2G NLV74VHC04DTR2G NLV27WZ00USG NLU1G86CMUTCG NLU1G08CMUTCG NL17SZ32P5T5G
NL17SZ00P5T5G NL17SH02P5T5G 74AUP2G00RA3-7 NLVVHC1GT00DFT2G NLV74HC02ADTR2G NLX1G332CMUTCG
NLVHCT132ADTR2G NL17SG86P5T5G NL17SZ05P5T5G NLV74VHC00DTR2G NLVVHC1G02DFT1G NLV74HC86ADR2G
74LVC2G86RA3-7 NL17SZ38DBVT1G NLV18SZ00DFT2G NLVVHC1G07DFT1G NLVVHC1G02DFT2G